



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-03-10
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

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**Legal statement**

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32L476JGY6STR	EB3F*415CCC4	A	997C	2025-03-10
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	21	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
1	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Tin/Silver/Copper (SAC405)	Not Applicable	NAC	0	
Package designator	Package size	Number of instances	Shape	
WLCSP	NA	72	Bulk solder	
Comment	Package : A02R WLCSP 72L DIE 415 PITCH 0.4 MM 8558904			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-21st January 2025				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	EB3F*415CCC4		20.7133		1000000.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	13.406	mg	supplier	die	Silicon (Si)	7440-21-3		12.836	mg	957481	619697.97
				supplier	metallization	Aluminium (Al)	7429-90-5		0.027	mg	2014	1303.50
				supplier	metallization	Copper (Cu)	7440-50-8		0.242	mg	18052	11683.56
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	75	48.54
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.078	mg	5818	3765.51
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	224	144.98
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	149	96.44
				supplier	Passivation	Silicon Nitride	12033-89-5		0.061	mg	4550	2944.84
				supplier	Passivation	Silicon Oxide	7631-86-9		0.156	mg	11637	7531.66
				supplier	Coating film	Silica	Proprietary		0.433	mg	574000	20908.36
				supplier	Coating film	Epoxy resin	Proprietary		0.161	mg	213000	7758.68
				supplier	Coating film	Acrylic resin	Proprietary		0.161	mg	213000	7758.68
Solder ball SAC405		3.806	mg	supplier	Solder ball	Tin	7440-31-5		3.634	mg	955000	175461.92
				supplier	Solder ball	Silver	7440-22-4		0.152	mg	4000	7349.19
				supplier	Solder ball	Copper	7440-50-8		0.019	mg	5000	918.65
Repassivation polymer(LTC9320)		0.336	mg	supplier	Repassivation polymer	Other polyamide resin	Proprietary	0.336	mg	1000000	16221.46	
RDL metallization(Ti)		0.008	mg	supplier	Runner/UBM (Metal Sputter)	Titanium	7440-32-6	0.008	mg	1000000	399.37	
RDL metallization(Cu)		0.033	mg	supplier	Runner/UBM (Metal Sputter)	Copper	7440-50-8	0.033	mg	1000000	1572.89	
UBM metallization(Ti)		0.008	mg	supplier	Runner/UBM (Metal Sputter)	Titanium	7440-32-6	0.008	mg	1000000	399.37	
UBM metallization(Cu)		0.033	mg	supplier	Runner/UBM (Metal Sputter)	Copper	7440-50-8	0.033	mg	1000000	1572.89	
RDL Copper		0.977	mg	supplier	RDL Copper	Copper	7440-50-8	0.977	mg	1000000	47186.67	
UBM Copper		1.352	mg	supplier	UBM Copper	Copper	7440-50-8	1.352	mg	1000000	65274.89	